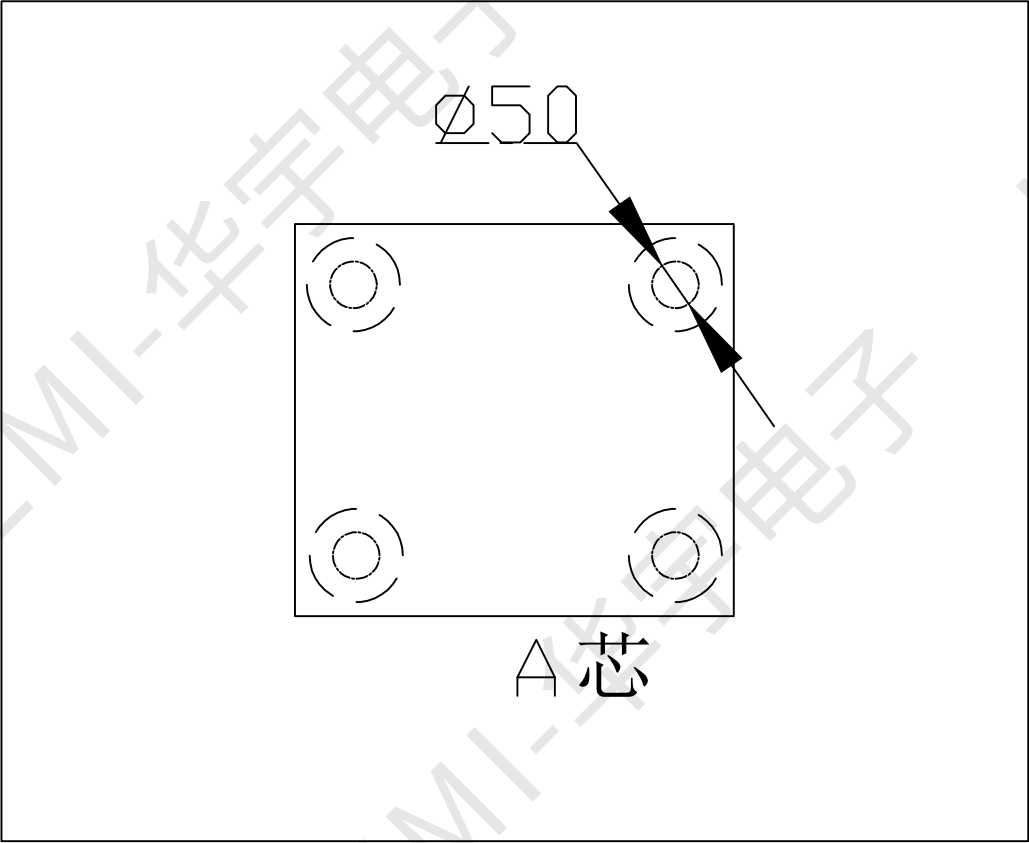


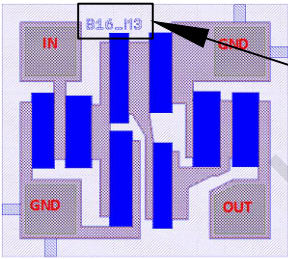
 池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram			客户代码 Customer No.		1200		线号 Drawing No.		HY-PX-1200-002 A			页码 Page 1 / 2			
			产品名称 Product Type		SSF244211D1-MP01-2021-01				封装外型 PKG Type		FCLGA5L(1.1X0.9X0.55-P0.4)				
助焊剂 Flux		橡胶吸嘴 pick collet		锡铜吸嘴 bond collet		蘸胶盘 flux plate		顶针 ejector		/		塑封料型号(绿色环保) Compound Type (Green)		基板编码 Substrate No.	
WS801PM		0.17#0.17mil		0.4*0.2mm		40UM		3mil		/		首选(Preferred): KE-G1250 备选(Optional):		LGA5L(011009)1200002	
客户图号 Customer drawing NO.															

样品验证，禁止量产！

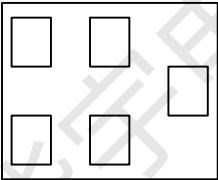
PIN1



A 芯

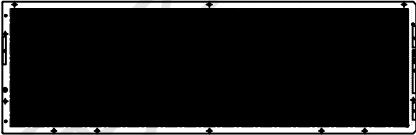


bump面 正视图(贴装前)

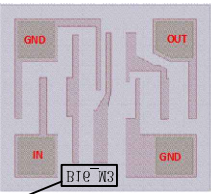


底部示意图

框架传送方向(装片):
L/F Direction (D/A): 三圆孔朝上



实物图:
Chip photo:



TOP面 透视图(贴装后)

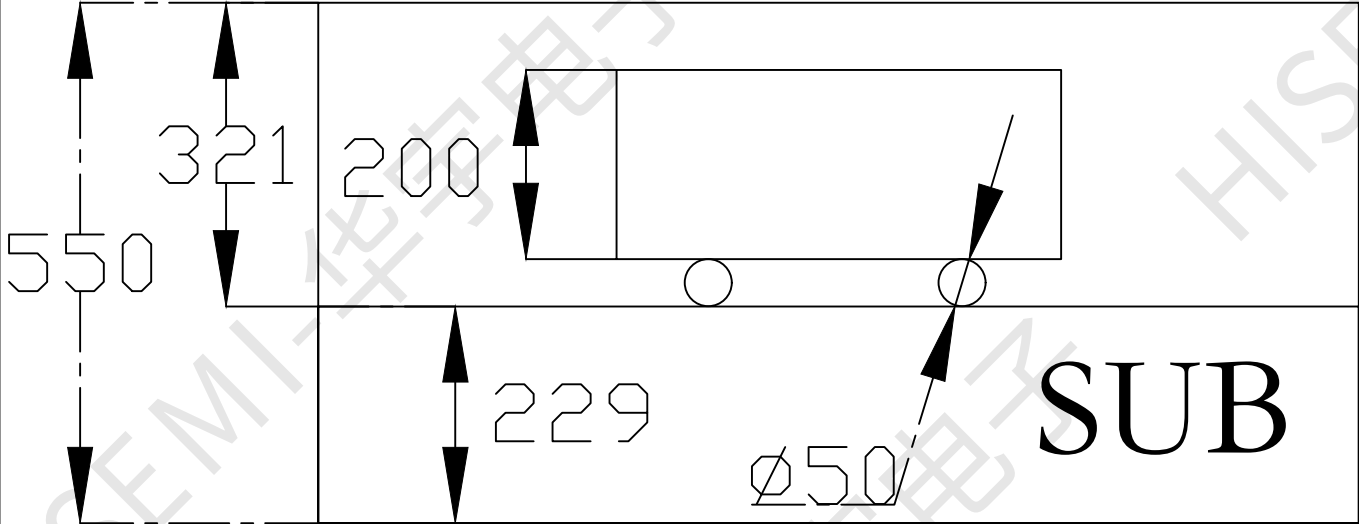
特殊说明 Special Instructions:

注意:
1.装片位置公差为±25um;

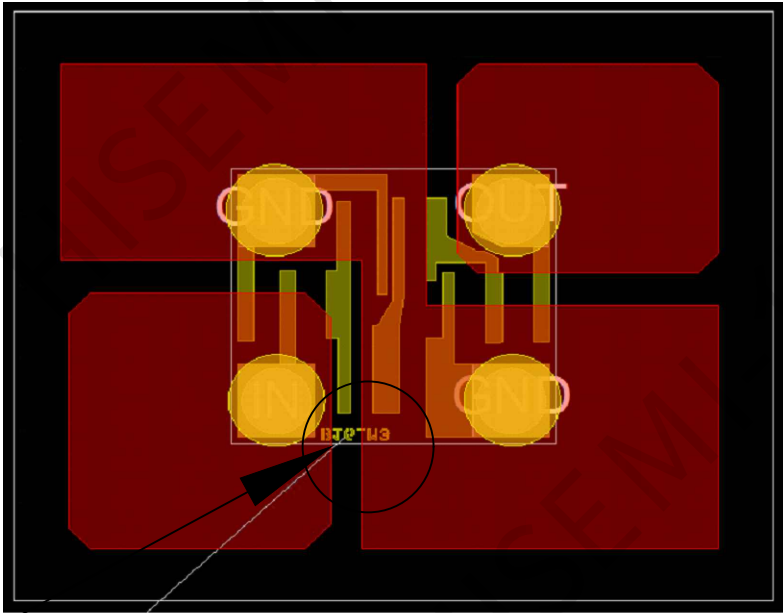
序号	芯片名称	Die ID	芯片尺寸	划片道 宽度	晶圆 尺寸	圆片 工艺	芯片厚度 UM	是否已 做磨 划	Wafer material*	Bump type*	Bump composition*	Min bump pitch (space + bump size)* UM	Min bump height* UM	Min bump diameter* UM
A芯	WK0073	B16_M3	470*420(μm²) 18.50*16.54(mil²)	54um	6寸	N0	200um (不包含 bump高度)	否	LT	Solder bump	SnAgCu	350um	50um	80um
拟制 Prepared by					制图日期 Create Date		2025/2/28		生效日期 Effective Date				客户确认签字/盖章: Customer Signature	
研发审核 R&d check					产品工程审核 Product engineering check				批准 Approved by					

*温馨提示: 图纸为产品下线生产的唯一依据, 请您认真确认, 我司依据您回签后的图纸生产, 如图纸错误会产生不可估量损失, 谢谢!
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

样品验证，禁止量产！



组装透视图



LOGO